

BS EN 60749-20-1:2009



BSI British Standards

Semiconductor devices – Mechanical and climatic test methods —

Part 20-1: Handling, packing, labelling and
shipping of surface-mount devices sensitive
to the combined effect of moisture and
soldering heat

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National foreword

This British Standard is the UK implementation of EN 60749-20-1:2009. It is identical to IEC 60749-20-1:2009.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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Amendments issued since publication

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